

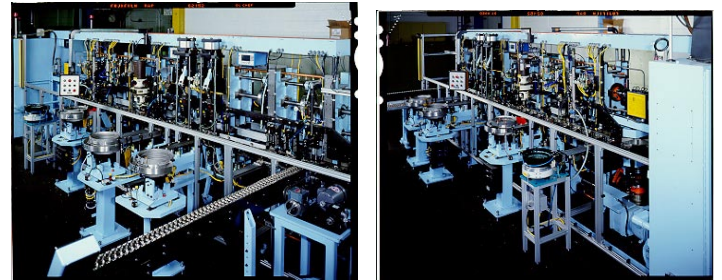
High Speed Data Port Connector Assembly

Ever increasing transmission rates for data forced all telecommunications equipment manufacturers to constantly upgrade and redesign their products to adapt to the market needs. This manufacturer of high speed data ports teamed up with the Bodine technical group while the product was still somewhat fluid, allowing them to take advantage of the "Design For Assembly" expertise that was available. The new connector needed to be assembled at high speed, and with great precision. Contact wire forming and positioning within the housing was absolutely critical to the functionality of the product. This made the Bodine Chassis the ideal platform.



System Overview

The system would be made up of three modules: On the PCB (printed circuit board) Module, (8)IDCs (insulation displacement contacts) are processed and inserted into zero clearance holes in the PCB. Additionally (2) sets of precision formed wire lead frames are pressed into the PCB. The Solder Module uses a thermal carrier puck on a conveyor system to send subassemblies through the solder reflow oven. The Final Module allows the soldered PCB to be assembled into its plastic housing. Labeling, ultrasonic welding, final wire form die cutting, and functional electric testing all follow with good assemblies being laser marked.



System Values & Benefits

- Standard platform ensures proven performance results.
- 100% vision verification of critical features.
- Quick change mounting for Die sets to allow for minimal downtime to facilitate die maintenance.

System Highlights

- System Operating Speed :50 ppm
- Gross Production Rate : 3000 assemblies/hour
- High Precision Placements Prevent Wire Damage
- Vision Verification of All Critical Placements and Dimensions
- Components are Fed from Coil Stock, Die Cut and Transferred.
- Protective Puck Pallets used in Solder Process.